



STP20NF06 STF20NF06

N-CHANNEL 60V - 0.06 Ω - 20A TO-220/TO-220FP STripFET™ II POWER MOSFET

Table 1: General Features

TYPE	V _{DSS}	R _{DS(on)}	I _D
STP20NF06	60 V	< 0.07 Ω	20 A
STF20NF06	60 V	< 0.07 Ω	20 A(*)

- TYPICAL R_{DS(on)} = 0.06 Ω
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- 175°C OPERATING TEMPERATURE
- HIGH dv/dt CAPABILITY
- APPLICATION ORIENTED CHARACTERIZATION

DESCRIPTION

This Power MOSFET is the latest development of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility

APPLICATIONS

- DC MOTOR CONTROL
- DC-DC & DC-AC CONVERTERS

Figure 1: Package

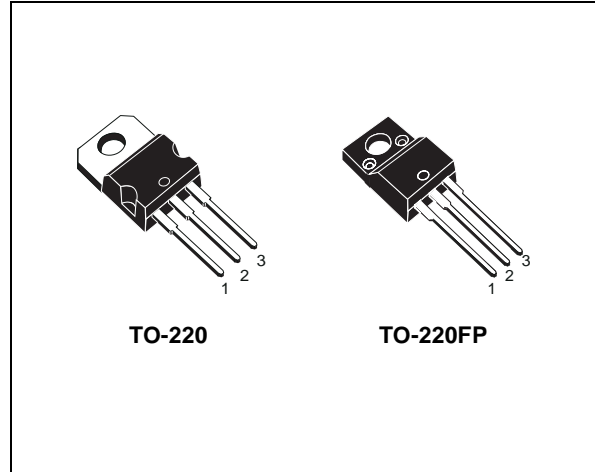


Figure 2: Internal Schematic Diagram

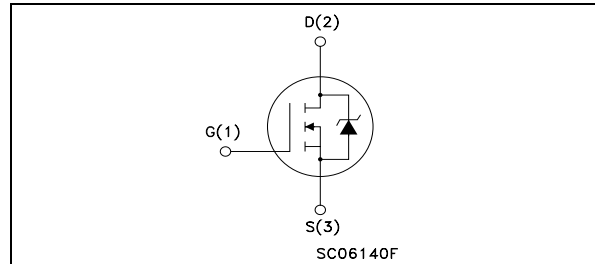


Table 2: Order Codes

Part Number	MARKING	PACKAGE	PACKAGING
STP20NF06	P20NF06	TO-220	TUBE
STF20NF06	F20NF06	TO-220FP	TUBE

Table 3: ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		STP20NF06	STF20NF06	
V _{DS}	Drain-source Voltage (V _{GS} = 0)	60		V
V _{DGR}	Drain-gate Voltage (R _{GS} = 20 k Ω)	60		V
V _{GS}	Gate- source Voltage	± 20		V
I _D	Drain Current (continuous) at T _C = 25°C	20	20(*)	A
I _D	Drain Current (continuous) at T _C = 100°C	14	14(*)	A
I _{DM} (•)	Drain Current (pulsed)	80	80(*)	A
P _{tot}	Total Dissipation at T _C = 25°C	60	28	W
	Derating Factor	0.4	0.18	W/°C
dv/dt (1)	Peak Diode Recovery voltage slope	9		V/ns
E _{AS} (2)	Single Pulse Avalanche Energy	120		mJ
T _{stg}	Storage Temperature	-55 to 175		°C
T _j	Operating Junction Temperature			

(•) Pulse width limited by safe operating area.

(*) Refer to soa for the max allowable current value on FP-type due to R_{th} value

(1) I_{SD} \leq 20A, di/dt \leq 200A/ μ s, V_{DD} \leq V_{(BR)DSS}, T_j \leq T_{JMAX}

(2) Starting T_j = 25 °C, I_D = 10A, V_{DD} = 30V

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Table 4: THERMAL DATA

		TO-220	TO-220FP	
Rthj-case	Thermal Resistance Junction-case Max	2.5	5.35	°C/W
Rthj-amb T _I	Thermal Resistance Junction-ambient Max Maximum Lead Temperature For Soldering Purpose	62.5 300		°C/W °C

ELECTRICAL CHARACTERISTICS (T_{CASE} = 25 °C UNLESS OTHERWISE SPECIFIED)

Table 5: OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	I _D = 250 µA, V _{GS} = 0	60			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V _{DS} = Max Rating V _{DS} = Max Rating T _C = 125°C			1 10	µA µA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 20V			±100	nA

Table 6: ON (5)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} I _D = 250 µA	2	3	4	V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10 V I _D = 10 A		0.06	0.07	Ω

Table 7: DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g _{fs} (5)	Forward Transconductance	V _{DS} = 15 V I _D = 8 A		10		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V _{DS} = 25V f = 1 MHz V _{GS} = 0		400 100 40		pF pF pF

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ELECTRICAL CHARACTERISTICS (continued)

Table 8: SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on Delay Time Rise Time	$V_{DD} = 30\text{ V}$ $I_D = 10\text{ A}$ $R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$ (Resistive Load, Figure)		5 15		ns ns
Q_g Q_{gs} Q_{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 30\text{ V}$ $I_D = 20\text{ A}$ $V_{GS} = 10\text{ V}$		14 3.0 5.5	18	nC nC nC

Table 9: SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(off)}$ t_f	Turn-off Delay Time Fall Time	$V_{DD} = 30\text{ V}$ $I_D = 10\text{ A}$ $R_G = 4.7\ \Omega$, $V_{GS} = 10\text{ V}$ (Resistive Load, Figure 3)		15 5		ns ns

Table 10: SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM}^{(1)}$	Source-drain Current Source-drain Current (pulsed)				20 80	A A
$V_{SD}^{(2)}$	Forward On Voltage	$I_{SD} = 20\text{ A}$ $V_{GS} = 0$			1.5	V
t_{rr} Q_{rr} I_{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 20\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 20\text{ V}$ $T_j = 150^\circ\text{C}$ (see test circuit, Figure 5)		50 80 3.2		ns μC A

(1) Pulse width limited by safe operating area.

(2) Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.

Figure 3: Safe Operating Area for TO-220

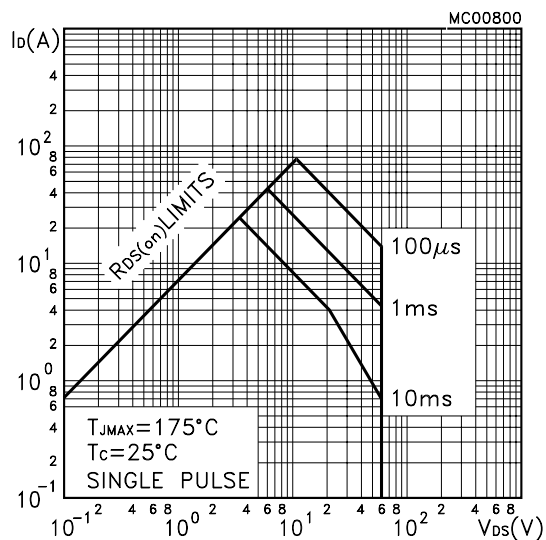


Figure 4: Safe Operating Area for TO-220FP

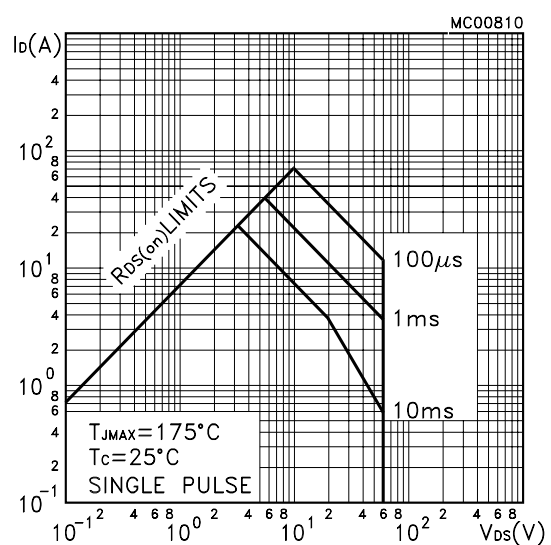


Figure 5: Thermal Impedance

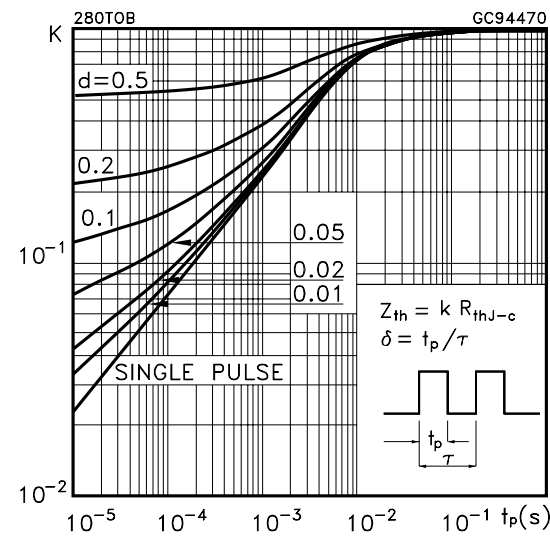


Figure 6: Thermal Impedance for TO-220FP

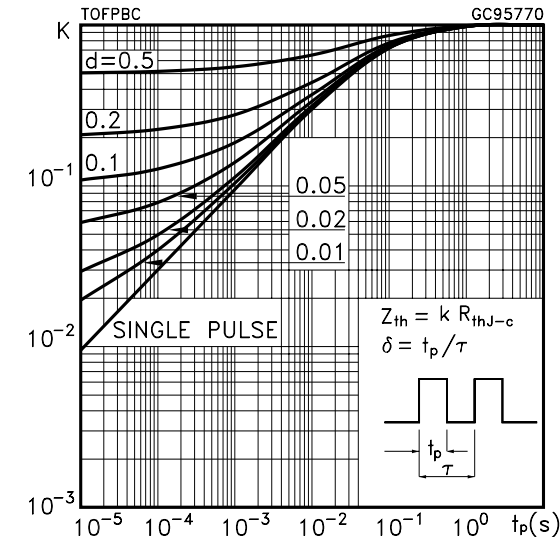


Figure 7: Output Characteristics

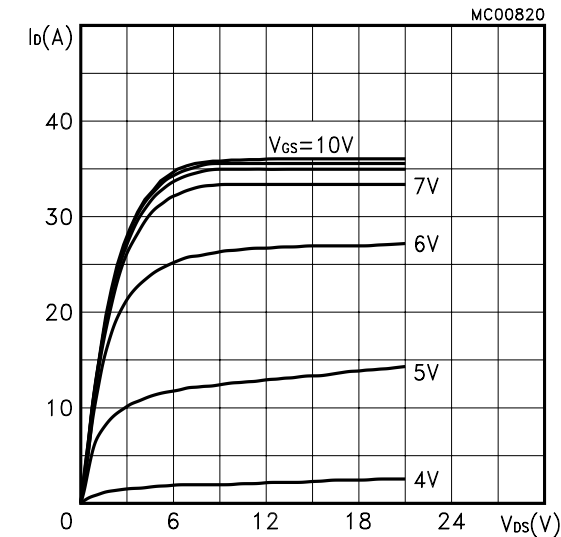


Figure 8: Transfer Characteristics

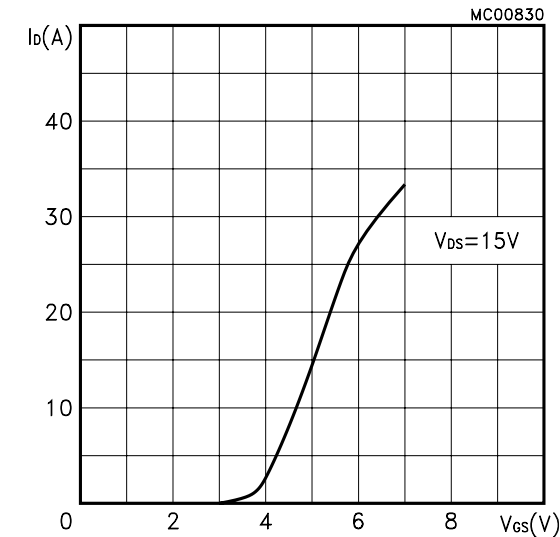


Figure 9: Transconductance

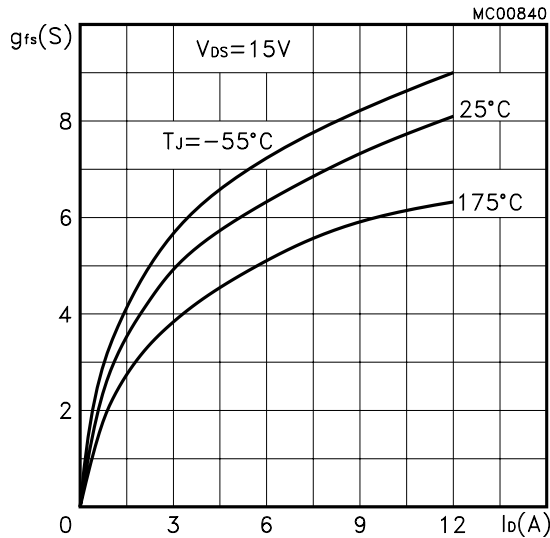


Figure 10: Static Drain-source On Resistance

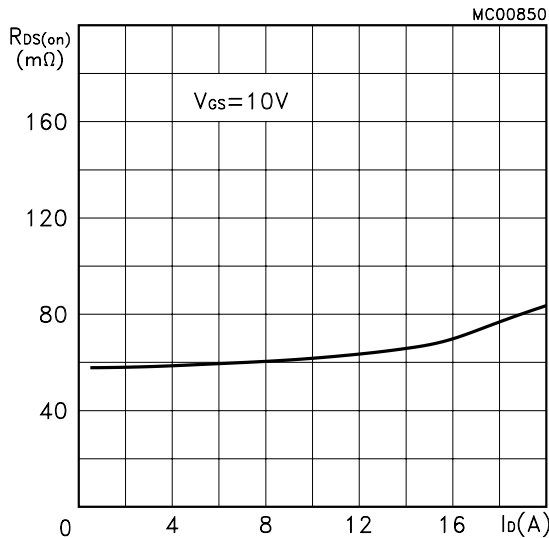


Figure 11: Gate Charge vs Gate-source Voltage

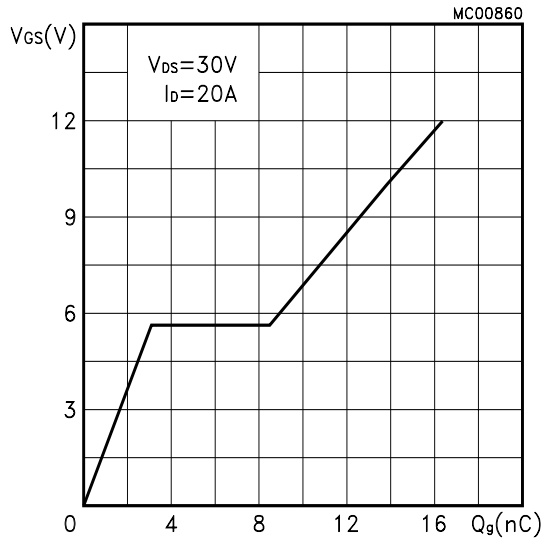


Figure 13: Normalized Gate Threshold Voltage vs Temperature

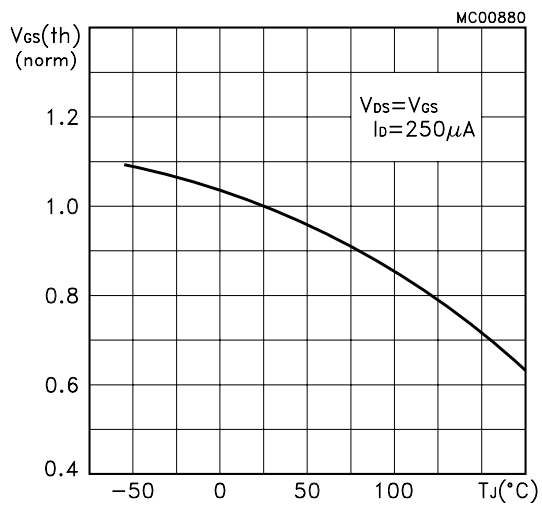


Figure 15: Source-drain Diode Forward Characteristics

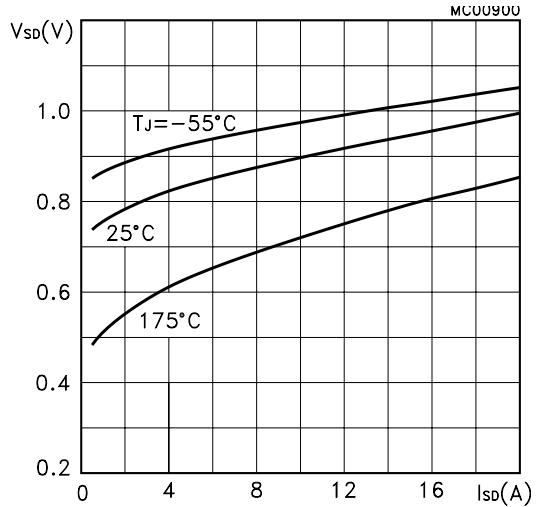


Figure 12: Capacitance Variations

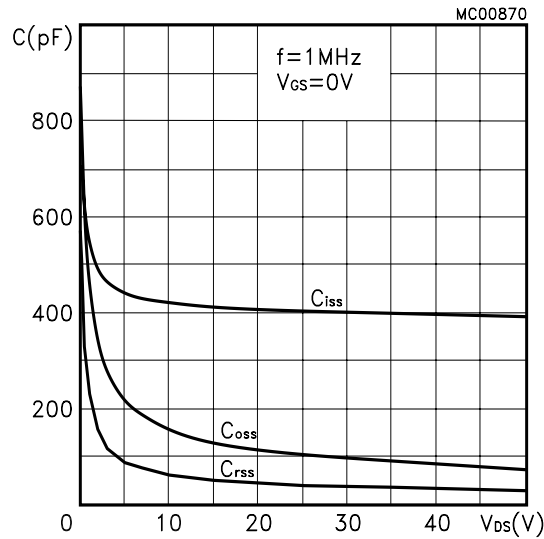


Figure 14: Normalized on Resistance vs Temperature

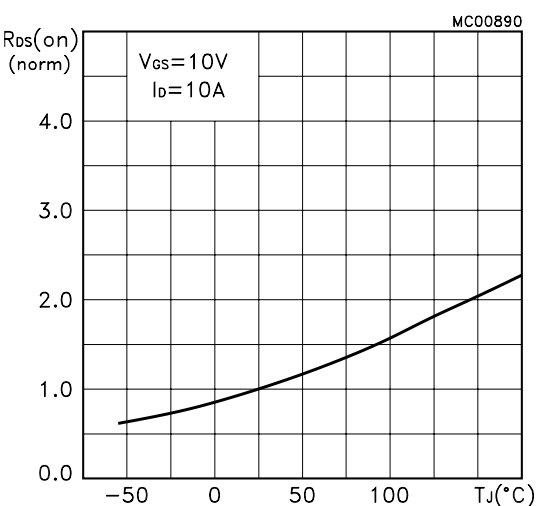


Figure 16: Normalized Breakdown Voltage Temperature

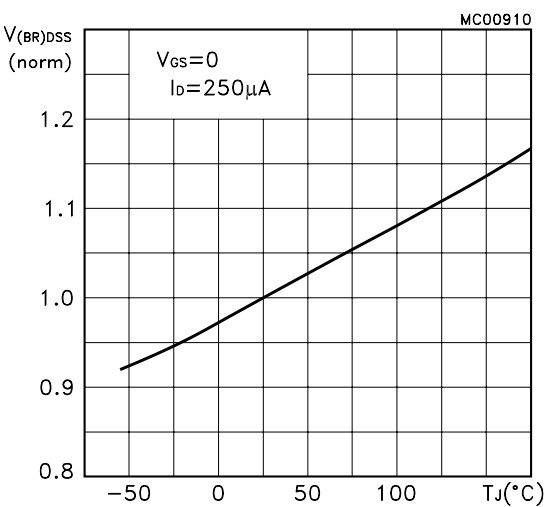


Figure 17: Unclamped Inductive Load Test Circuit

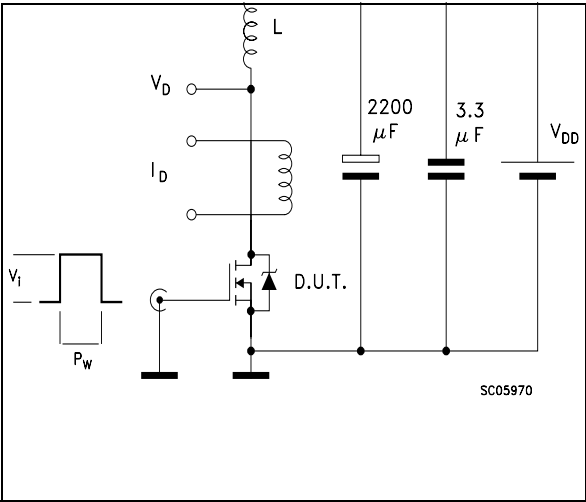


Figure 18: Unclamped Inductive Waveform

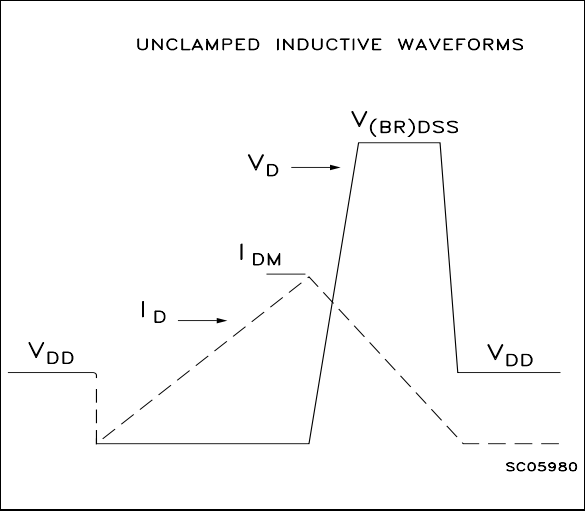


Figure 19: Switching Times Test Circuits For Resistive Load

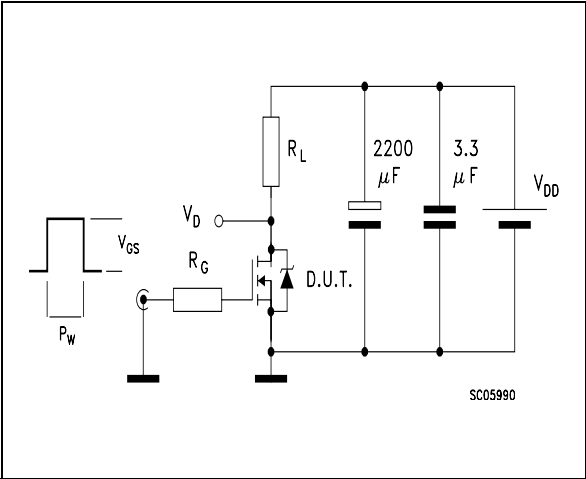


Figure 20: Gate Charge test Circuit

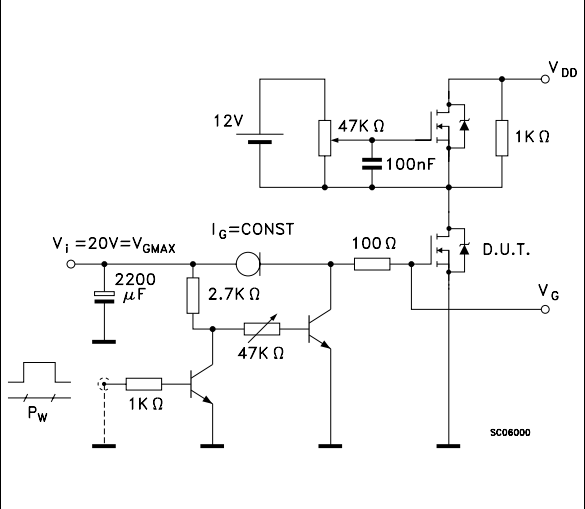
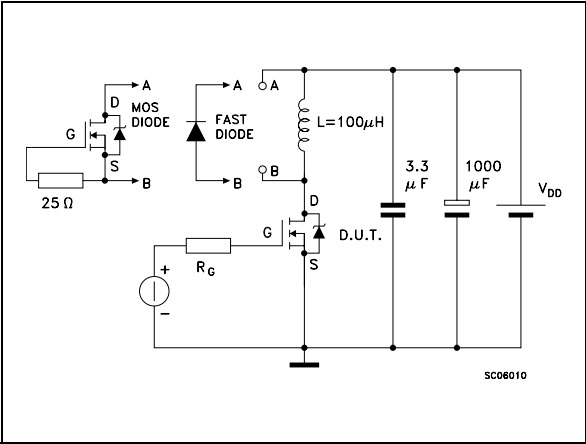
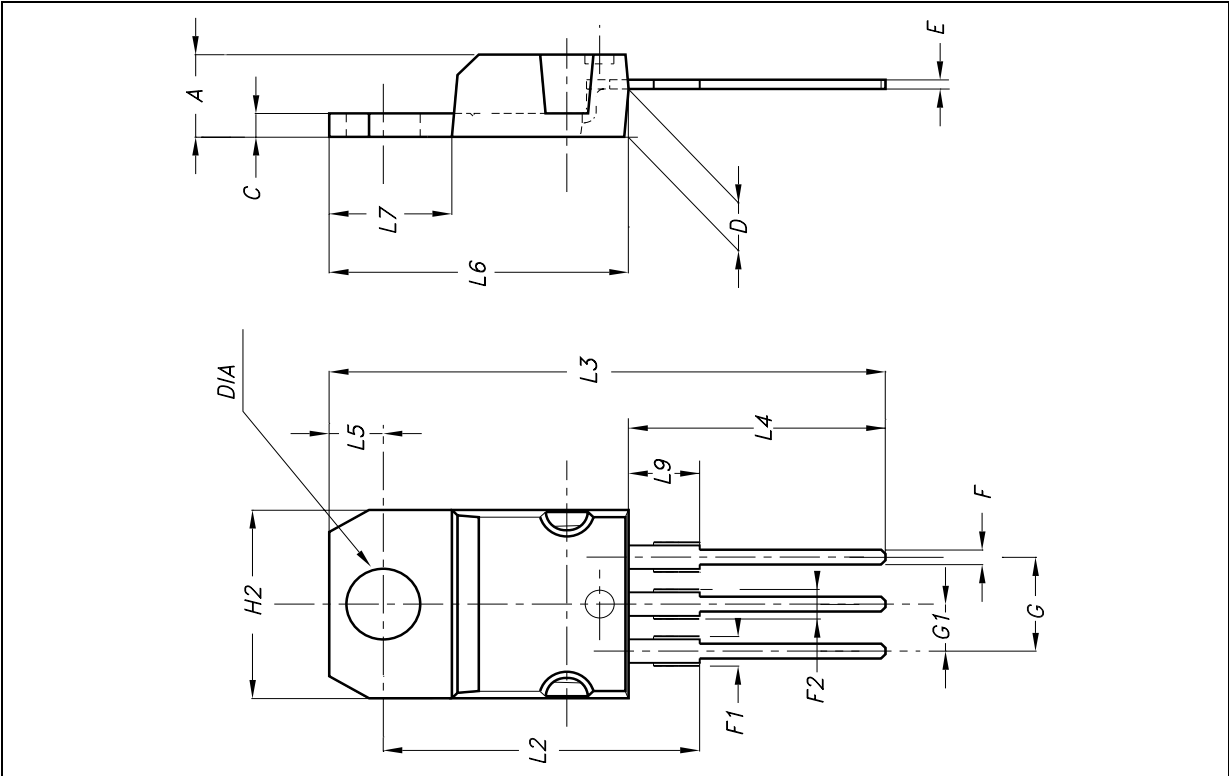


Figure 21: Test Circuit For Inductive Load Switching And Diode Recovery Times



TO-220 MECHANICAL DATA

DIM.	mm.			inch.		
	MIN.	TYP.	MAX.	MIN.	TYP.	TYP.
A	4.4		4.6	0.173		0.181
C	1.23		1.32	0.048		0.051
D	2.40		2.72	0.094		0.107
E	0.49		0.70	0.019		0.027
F	0.61		0.88	0.024		0.034
F1	1.14		1.70	0.044		0.067
F2	1.14		1.70	0.044		0.067
G	4.95		5.15	0.194		0.203
G1	2.40		2.70	0.094		0.106
H2	10		10.40	0.393		0.409
L2		16.40			0.645	
L3		28.90			1.137	
L4	13		14	0.511		0.551
L5	2.65		2.95	0.104		0.116
L6	15.25		15.75	0.600		0.620
L7	6.20		6.60	0.244		0.260
L9	3.50		3.93	0.137		0.154
DIA	3.75		3.85	0.147		0.151



TO-220FP MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
H	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	0.385		0.417
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126

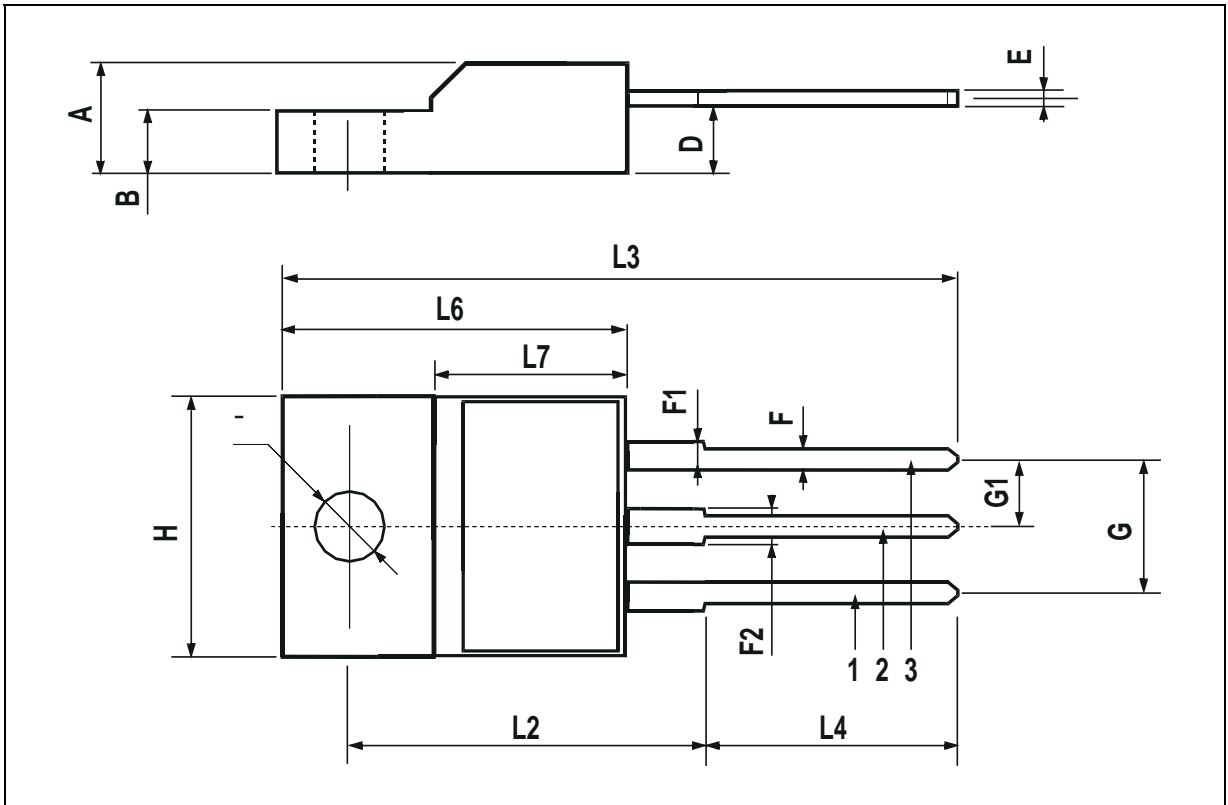


Table 11:Revision History

Date	Revision	Description of Changes
07-Nov-2004	1.0	FIRST ISSUE

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